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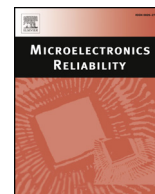
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Editorial

Special issue: International conference on thermal, mechanical & multiphysics simulation and experiments in micro- and nano-electronics and systems [EuroSimE2017]



On behalf of the Editorial Board, we are pleased to propose a selection of papers presented at the 18th IEEE International Conference on Thermal, Mechanical and Multiphysics Simulation and Experiments in Microelectronics and Microsystems (EuroSimE 2017) held in Dresden, Germany, from 3 to 5 April 2017 (www.eurosim.org). EuroSimE was created as the only annual international conference with a focus on thermal, mechanical and multiphysical simulations and experiments for microelectronics and microsystems.

The first conference was initiated in 2000 by the COMPETE network, with sponsorship from the European Commission, to meet research and development needs in the fields of Microelectronics and Microsystems. Since then, EuroSimE has garnered worldwide attention with participants from more than thirty countries, spanning all continents, and has become a fully sponsored IEEE CPMT technical event. The conference proceedings are part of the IEEE conference publication program and can be found in both the IEL and IEEE Xplore R systems, a total of 1376 papers are the output of the EuroSimE history. The EuroSimE conference has earned a reputation for high scientific and technical quality.

The 18th edition was organized by the Fraunhofer Institute for Ceramic Technologies and Systems IKTS in the city of Dresden (Germany). EuroSimE 2017 attracted 160 participants. Among the more than 90 papers presented in the conference, 15 papers were chosen for this Special Issue. Following a rigorous review, 10 papers were finally

selected for publication. Multiphysical micro- and nano-electronics have an ever-increasing impact on our lives as industry creates a wealth of new products based on them. The selected papers in this special section cover a broad technical scope including color characterization and color maintenance in Light Emitting Diodes (LEDs), characterization of electronic packaging materials (silicones, solders and epoxies), reliability assessments of new technologies (inkjet-printed sensors, thermo-optical filters, copper pillars) and the analysis microfluidic flow chambers. All these papers represent the state-of-the-art and future development trends for all the disciplines associated with this conference.

We hope that this special section can be helpful for your work. We would also like to have your feedback and suggestions for improving our work, and to provide you with valuable references in the future. We would also like to sincerely thank the Journal of Microelectronic Reliability for its editorial support to the preparation of this issue and constant assistance.

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